

Substitute for form 1449/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  Sheet 1 of 2	<b>Complete if Known</b>	
	<b>Application Number</b>	10/053,340
	<b>Filing Date</b>	10/22/2001
	<b>First Inventor</b>	WARE, Frederick
	<b>Art Unit</b>	2187
	<b>Examiner</b>	Nguyen, Than
	<b>Atty Docket #</b>	RBS2.P049
	<b>Rambus #</b>	RA207.CIP1.US

US Patent Documents						
Examiner Initials*	Cite No.	Document No.	Date (MM-DD-YYYY)	Patentee	Class	Subclass
	0000040	4656605	04/07/1987	Clayton	365	52
	0000262	5606717	02/25/1997	Farmwald, et al.	710	36
	0000767	5742798	04/21/1998	Goldrian	395	551
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	0001080	5867541	02/02/1999	Tanaka et al.	375	354
	0001083	6336205	01/01/2002	Kurokawa et al.	716	2
	0001297	5796624	08/18/1998	Sridhar et al.	364	489
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Examiner Initials*	Cite No.	Cty	Document No.	Date (MM-DD-YYYY)	Patentee	Class	Subclass	T**
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	0007642	JP	2000348490	12/15/2000	Hitachi Ltd.	G11C	11/413	
	0007643	JP	11284126	10/15/1999	Fujitsu Ltd.	H01L	25/16	
	0007644	WO	9815897	04/16/1998	Hewlett-Packard Company	G06F	13/16	
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	0007969	JP	2008227394	09/03/1996	Monolithic System Technology, Inc.	G06F	13/40	

<b>Examiner Signature:</b>	/Than Nguyen/	<b>Date Considered:</b>	08/22/2008
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. **Applicant is to place a check mark here if English language Translation is attached.			

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /T.N./

Substitute for form 1449/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  Sheet 2 of 2	<b>Complete if Known</b>	
	<b>Application Number</b>	10/053,340
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	<b>First Inventor</b>	WARE, Frederick
	<b>Art Unit</b>	2187
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	<b>Atty Docket #</b>	RBS2.P049
	<b>Rambus #</b>	RA207.CIPI.US

Foreign Patent Documents								
Examiner Initials*	Cite No.	Cty	Document No.	Date (MM-DD- YYYY)	Patentee	Class	Subclass	T**
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Non-Patent Literature Documents				
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		T**
	0003940	RAMBUS INC. Data Sheet, "8/9-Mbit (1M x 8/9) and 16/18-Mbit (2M x 8/9) RDRAM", March 1996, pages 1-30		
	0003966	RAMBUS INC., Rambus RIMM Module (with 64/72Mb RDRAMs) Data Sheet, Preliminary Information, Document DL0078 Version 0.90, March 1999, pages 1 - 11		
	0004073	RAMBUS, INC. Direct Rambus Short Channel Layout Guide, Version 0.8, March 2000, 34 pages		
	0004320	"Standard for a High-Speed Memory Interface (SyncLink)," IEEE Draft 0.99 IEEE P 1596.7 199X, 1996, 66 pages.		
	0004474	THE INSTITUTE OF ELECTRICAL AND ELECTRONICS ENGINEERS: "Standard for High-Bandwidth Memory Interface Based on Scalable Coherent Interface Signalling Technology (RamLink)" 19 March 1996 (1996-03-19), IEEE STD 1596.4-1996, XP002315223 * pages 12,43-45 *		
	0006661	International Preliminary Report on Patentability and Written Opinion of the International Searching Authority in International Application PCT/US2005/032346, European Patent Office, March 29, 2007, 10 pages.		
	0007023	International Preliminary Report and Written Opinion of the International Searching Authority in International Application PCT/US/2005/032770, World Intellectual Property Organization, April 12, 2007, 6 pages. (RBS2.P034WO)		
	0007024	International Search Report and Written Opinion of the International Searching Authority in International Application PCT/US2005/042722, World Intellectual Property Organization, May 10, 2006, 15 pages. (RBS2.P011WO)		
	0007597	YEUNG et al., 2000, "A 2.4 Gb/s/pin Simultaneous Bidirectional Parallel Link with Per-Pin Skew Compensation," IEEE Journal of Solid-State Circuits, Vol. 35, No. 11, Pages 1619-1627		
	0008004	Notice of Opposition to European Patent No. 1291778; Application No. 02009032.0; 24 pages		

<b>Examiner Signature:</b>	/Than Nguyen/	<b>Date Considered:</b>	08/22/2008
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